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To: Commissioner of Patents and Trademarks
Washington, D.C. 20231

Fr: George O. Saile, Reg. No. 19,572
20 McIntosh Drive
Poughkeepsie, N.Y. 12603

Technology Center 2600

JAN 11 2002

RECEIVED

Subject:

Serial No. 09/970,788 10/05/01

Devendra S. Chhabra, Glen Garfunkel,
Rod Lee, Morris Dovek, C.C. Han

THERMAL PROTRUSION REDUCTION IN
MAGNET HEADS BY UTILIZING A HEAT-
SPREADING PAD

Grp. Art Unit: 2652

INFORMATION DISCLOSURE STATEMENT

Enclosed is Form PTO-1449, Information Disclosure Citation
In An Application.

The following Patents and/or Publications are submitted to
comply with the duty of disclosure under CFR 1.97-1.99 and
37 CFR 1.56. Copies of each document is included herewith.

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being
deposited with the United States Postal Service as first class
mail in an envelope addressed to: Commissioner of Patents and
Trademarks, Washington, D.C. 20231, on ~~November 13~~ ^{Dec}, 2001.

Stephen B. Ackerman, Reg.# 37761

Signature/Date

 12/13/01

U.S. Patent 5,936,811 to Seagle, "Magnetic Head with Vialess Lead Layers from MR Sensor to Pads," provides a slider assembly in which the current carrying leads are disposed in a manner that eliminates the need for vias passing through the insulating layers and shield layers to allow the electrical activation of the read and write sensors.

U.S. Patent 6,158,107 to Chang et al., "Inverted Merged MR Head with Plated Notched First Pole Tip and Self-Aligned Second Pole Tip," provides a merged read/write head in which the pole tips of the write head are more advantageously defined by use of a self-alignment formation process and show the use of a substantial overcoat in the head formation.

U.S. Patent 3,770,403 to Maries et al., "Method of Making Magnetic Head Assembly Having Glass Ceramic Bonded Parts," discloses a magnetic head assembly in which the read/write circuit portions of the assembly are formed on a chip and bonded to head assembly by a glass-ceramic material whose coefficient of expansion matches the coefficient of expansion of the parts to be joined.

U.S. Patent 6,103,136 to Han et al., "Method for Forming a Soft Adjacent Layer (SAL) Magnetoresistive (MR) Sensor Element with Transversely Magnetically Biased Soft Adjacent Layer (SAL)," discloses a magnetoresistive read head.

U.S. Patent 5,757,590 to Phipps et al., "Fusible-Link Removable Shorting of Magnetoresistive Heads for Electrostatic Discharge Protection," discloses the problem of electrostatic charge buildup on read/write heads, which is another problem associated with rapid relative movement between the head and the recording medium.

U.S. Patent 6,130,863 to Wang et al., "Slider and Electro-Magnetic Coil Assembly," discloses the use of a magnetic coil and slider assembly even in the field of magneto-optical storage systems.

Sincerely,


Stephen B. Ackerman,
Reg. No. 37761